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(71) Applicant (for all designated States except US): **CANON KABUSHIKI KAISHA** [JP/JP]; 3-30-2, Shimomaruko, Ohta-ku, Tokyo 1468501 (JP).

(72) Inventors; and

(75) Inventors/Applicants (for US only): **SHINKAI, Michinori** [JP/JP]; c/o Canon Kabushiki Kaisha, 3-30-2, Shimomaruko, Ohta-ku, Tokyo 1468501 (JP). **SUZUKI,**

Satoshi [JP/JP]; c/o Canon Kabushiki Kaisha, 3-30-2, Shimomaruko, Ohta-ku, Tokyo 1468501 (JP).

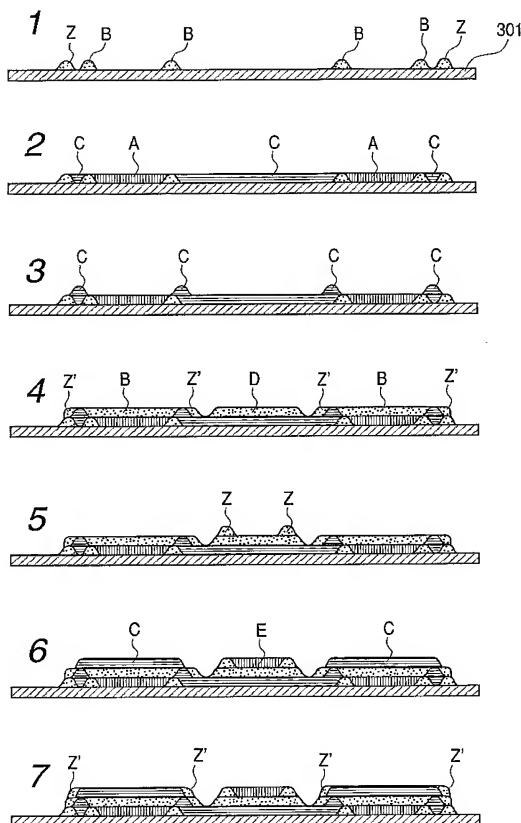
(74) Agents: **OKABE, Masao** et al.; No. 602, Fuji Bldg., 2-3, Marunouchi 3-chome, Chiyoda-ku, Tokyo 1000005 (JP).

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[Continued on next page]

(54) Title: WIRING FORMING METHOD, WIRING FORMING APPARATUS, AND WIRING BOARD



(57) Abstract: After performing one forming step of a first pattern forming step of forming a first pattern on a substrate and a second pattern forming step of forming a second pattern on the substrate, the other forming step is performed to thereby form a high-reliability wiring pattern on the substrate.

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